

U.S. Patent Documents

Examiner Initials	Document No.	Date	Name	Class Subclass	Filing Date If Approp.
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	5,272,417	12/93	Ohmi		
	5,283,414	2/94	Straemke (corresponds to DE 40 07 123 A1)		
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Document No.	Date	Country	Class Subclass	Translation Yes No
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3-64025	3/91	Japan			
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DDM "Suppression Shield for RF Plasma", W. J. Curry et al, IBM Technical Disclosure Bulletin, Vol. 22, No. 11, April 1980, pp 4909-4910

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